



PATENT

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANTS : Xm WONG et al.
SERIAL NO. : 09/741,684
FILED : December 18, 2000
FOR : BONDING PAD OF SUSPENSION CIRCUIT
GROUP ART UNIT : 2652
EXAMINER : Brian E. MILLER

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Technology Center 2600

M/S: NON-FEE AMENDMENTS
Commissioner for Patents
P.O. Box 1450
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Date: October 16, 2003

Barbara Vance
Signature

Barbara Vance

AMENDMENT AND RESPONSE

Dear Sir:

The following remarks below are respectfully submitted in response to the Office Action dated July 14, 2003.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 4 of this paper.